

EDSFair2011 Exhibition Categories of Products to be Exhibited

1 Hardware solutions	System LSI	ASIC / ASSP	MPU / MCU / DSP	FPGA / PLD	Others	Analyzers	Others		
2 Hardware development (EDA)	i. IC design tools						5 IP core, Macro, Cell libraries		
	System level design (higher than RTL)						6 Embedded processor development environments		
	Logic design (RTL to net list)						Reconfigurable processors		
	Logic verification						ICE		
	Analog design / verification						Debuggers		
	Physical implementation						Microcomputer CASE		
	Physical verification / analysis						Compilers / Cross Compilers		
	Signal integrity analysis						Simulators		
	Test (DFT / BIST / ATPG / others)						Hardware / Software co-design environments		
	DFM (OPC / RET / PSM / LRC / CAD / others)						Others		
	ASIC Prototyping						7 Design service-related (LSI / PCB)		
	Others						Design houses		
ii. PCB / SiP design tools								Design services	
	Schematic capture						Design consulting,		
	Analog design / verification						Prototyping / Manufacturing		
	Layout						IP distribution services		
	Signal Integrity / Power Integrity / EMC analysis						Others		
	Electromagnetic field analysis						8 Design infrastructure (WS / PC, Network)		
	Thermal analysis						9 Design data management tool		
	Others						Design data management		
3 Software solutions								Others	
	Embedded OS						10 Mask shop, Foundry		
	Device drivers						11 University (R&D), Consortium		
	Firmware						12 PR-related		
	Middleware						Publications		
	Virtual platform / Development						Others		
	Others								
4 IC tester / analyzer									
	IC testers								
	PCB testers								

Exhibitor Seminar Categories

*may slightly change due to the number of applications

(A) ESL (including early SW development and virtual / HW prototyping)	(H) IP
(B) Low Power	(I) PCB
(C) Timing convergence	(J) DFT
(D) DFM	(K) Physical verification
(E) Reliability(Power integrity)	(L) Physical implementation
(F) AMS design / verification	(M) Design / Verification service
(G) Functional verification (including HW prototyping)	(N) Thermal / Fluid analysis
	(O) Others



electronic design and solution fair 2011

Exhibition Application Form

How to Apply

Please read the EDSFair 2011 Exhibition Regulations.

Fill in the required information on the application form, sign it and send it to the Show Management Office at (see below) by post.

www.edsfair.com/e/

2011

Send to:

Japan Electronics Show Association

12F Ote Center Bldg., 1-1-3 Otemachi,
Chiyoda-ku, Tokyo 100-0004, Japan
TEL : 81-3-6212-5231 FAX:81-3-6212-5225

Thursday, January 27 to Friday, January 28

PACIFICO YOKOHAMA

Sponsor:

JEITA Japan Electronics and Information Technology Industries Association

T0 Japan Electronics Show Association

Our company / organization will comply with all exhibition rules and regulations stipulated by both the Organizing Committee and Japan Electronics Show Association. In accordance with this agreement, we herewith submit the EDSFair 2011 Exhibition Application.



electronic design and solution fair 2011
EDSFair 2011 Exhibition Application Form

Early application deadline	Friday, Aug. 27, 2010
Secondary application deadline	Friday, Sep. 24, 2010
Date received	

For official use only

Confirmation	Recipient No.	Member	<input type="checkbox"/> Early	Entry Date	Invoice	Booth No.
			<input type="checkbox"/> Secondary			
			<input type="checkbox"/> Final			

Our company is a

<input type="checkbox"/> Previous EDSFair exhibitor	<input type="checkbox"/> First-time exhibitor (Please submit company profile and product catalogs.)
<input type="checkbox"/> Member of the Japan Electronics Show Association (JESA)	<input type="checkbox"/> Non-Member

Number of Booths applied for

Booth Configuration	Number applied for	Exhibition fee (tax included)	
<input type="checkbox"/> 1 row (1,2,3,4,5,6)	booth(s)	Apply by Aug. 27, 2010 @¥294,000 (standard fee)	= ¥
<input type="checkbox"/> 2 rows (4,6,8,10,12)		@¥262,500 (Member fee)	
<input type="checkbox"/> 3 rows (9,12,15,18)		Apply after Aug. 28, 2010 @¥304,500 (standard fee)	
<input type="checkbox"/> 4 rows (16)		@¥273,000 (Member fee)	
<input type="checkbox"/> Block format (20,25,30,35,40,45,50)			
<input type="checkbox"/> Emerging Company Packaged Booth	booth(s)	@¥210,000	= ¥

Exhibition Categories of Products to be Exhibited

Refer to Exhibition Categories of Products to be Exhibited on the reverse side and check all that apply to your product(s) to be exhibited.

<input type="checkbox"/> 1. Hardware solutions	<input type="checkbox"/> 5. IP core, Macro, Cell libraries	<input type="checkbox"/> 9. Design data management tool
<input type="checkbox"/> 2. Hardware development (EDA)	<input type="checkbox"/> 6. Embedded processor development environments	<input type="checkbox"/> 10. Mask shop, Foundry
<input type="checkbox"/> 3. Software solutions	<input type="checkbox"/> 7. Design service-related (LSI / PCB)	<input type="checkbox"/> 11. University (R&D), Consortium
<input type="checkbox"/> 4. IC tester / analyzer	<input type="checkbox"/> 8. Design infrastructure (WS / PC, Network)	<input type="checkbox"/> 12. PR-related

Exhibitor Seminar

Seminar Type	Number of Session	Room Charge (tax included)	
Regular (for 30~50 audiences)	session (s)	@ ¥52,500	= ¥
Large (up to 100 audiences)	session (s)	@¥126,000	= ¥

Preferred Exhibitor Seminar Date / Categories

Refer to Exhibitor Seminar Categories on the reverse side and fill the breakdown of the total number of applied sessions and fill categories in the blanks.

*may slightly change due to the number of applications.

Number of Session on Jan.27th	Categories (A-0)	Number of Session on Jan.28th	Categories (A-0)
Regular session (s)		Regular session (s)	
Large session (s)		Large session (s)	

Suites

Room type	Number of Room	Room Charge (tax included)	
S (3.96m×3.96m)	room (s)	@¥273,000	= ¥
M (5.94m×3.96m)	room (s)	@¥336,000	= ¥
L (5.94m×4.95m)	room (s)	@¥378,000	= ¥

Exhibitor Information

This information will appear in printed materials and on the official EDSFair website exactly as written, so please be careful to provide accurate information.

Please print using uppercase and lowercase letters, as appropriate.

Company Name (One letter per box, leave box empty for space)																				
Head Office Information	Address																			
	CEO'S Official Title													CEO'S Name						
Exhibition Supervisor	Address																			
	Title / Division													Name						
	TEL													FAX						
	E-mail																			
Invoice Address (Not necessary if same as above)	Address																			
	Title / Division													Name						
	TEL													FAX						
	E-mail																			
URL																				

On behalf of my company, I hereby acknowledge that I have read, understood and will comply with the EDSFair 2011 Exhibition Regulations and herewith apply to exhibit.

Person in charge of our exhibit
Company name:

Name (please print):

Job title:

Signature: